9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

FEATURES

- 5-volt tolerant inputs/outputs, for interfacing with 5-volt logic
- Supply voltage range of 2.7V to 3.6V
- Complies with JEDEC standard no. 8-1A
- Inputs accept voltages up to 5.5V
- CMOS low power consumption
- Direct interface with TTL levels
- 9-bit positive edge-triggered register
- Independent register and 3-State buffer operation
- Flow-through pin-out architecture

DESCRIPTION

The 74LVC823A is a high performance, low-power, low-voltage Si-gate CMOS device and superior to most advanced CMOS compatible TTL families.

Inputs can be driven from either 3.3V or 5.0V devices. In 3-state operation, outputs can handle 5V. This feature allows the use of these devices as translators in a mixed 3.3V/5V environment.

The 74LVC823A is a 9-bit D-type flip-flop with common clock (CP), Clock Enable (CE), Master Reset (MR) and 3-State outputs for bus-oriented applications.

The nine flip-flops will store the state of their individual D-inputs that meet the set-up and hold times requirements on the LOW-to-HIGH CP transition provided $\overline{\text{CE}}$ is LOW. When $\overline{\text{CE}}$ is HIGH the flip-flops hold their data.

A LOW on MR resets all flip-flops.

When \overline{OE} is LOW, the contents of the nine flip-flops is available at the outputs. When \overline{OE} is HIGH, the outputs go to the high impedance OFF-state. Operation of the OE input does not affect the state of the flip-flops.

QUICK REFERENCE DATA

GND = 0 V; $T_{amb} = 25$ °C; $t_r = t_f \le 2.5$ ns

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t _{PHL} /t _{PLH}	Propagation delay CP to Q _n	C _L = 50 pF; V _{CC} = 3.3 V	4.8	ns
f _{max}	Maximum clock frequency	C _L = 50 pF; V _{CC} = 3.3 V	150	MHz
C _I	Input capacitance		5.0	pF
C _{PD}	Power dissipation capacitance per flip-flop	Notes 1 and 2	27	pF

 C_{PD} is used to determine the dynamic power dissipation (P_D in μW)

 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

 f_i = input frequency in MHz; C_L = output load capacity in pF; f_o = output frequency in MHz; V_{CC} = supply voltage in V;

 $(C_L \times V_{CC}^2 \times f_0) = \text{sum of the outputs.}$

2. The condition is $V_I = GND$ to V_{CC}

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	ORDERING CODE	PKG. DWG. #
24-Pin Plastic SO	–40°C to +85°C	74LVC823A D	SOT137-1
24-Pin Plastic SSOP Type II	–40°C to +85°C	74LVC823A DB	SOT340-1
24-Pin Plastic TSSOP Type I	–40°C to +85°C	74LVC823A PW	SOT355-1

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PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1	ŌĒ	Output enable input (active LOW)
2, 3, 4, 5, 6, 7, 8, 9, 10	D ₀ to D ₈	Data inputs
11	MR	Master reset (active LOW)
12	GND	Ground (0 V)
13	СР	Clock pulse (active rising)
14	CE	Clock enable (active LOW)
23, 22, 21, 20, 19, 18, 17, 16, 15	Q ₀ to Q ₈	3-State flip-flop outputs
24	V _{CC}	Positive supply voltage

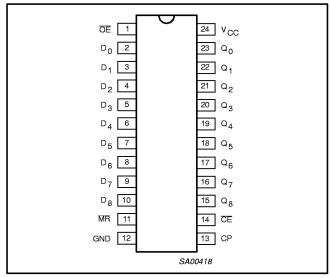
FUNCTION TABLE

ODEDATING MODES			INPUTS		INTERNAL FLIP-FLOPS	OUTPUTS	
OPERATING MODES	ŌĒ	MR	CE	СР	D _n	INTERNAL FLIP-FLOPS	Q ₀ to Q ₈
Clear	L	L	Х	Х	Х	L	L
Load and read register	L L	H H	L L	↑	l h	L H	L H
Load register and disable outputs	H H	H H	L L	X X	l h	L H	Z Z
Hold	L	Н	Н	NC	Х	NC	NC

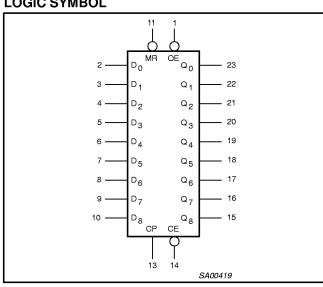
H = HIGH voltage level

NC= no change

PIN CONFIGURATION



LOGIC SYMBOL



⁼ HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition

⁼ LOW voltage level

LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition

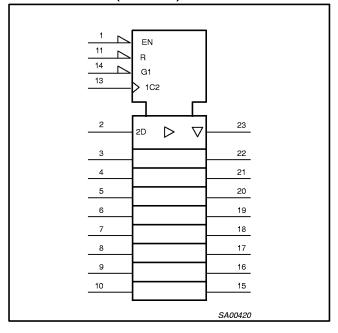
⁼ high impedance OFF-state

⁼ LOW-to-HIGH clock transition

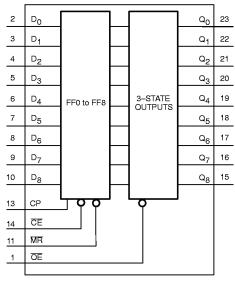
9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

LOGIC SYMBOL (IEEE/IEC)

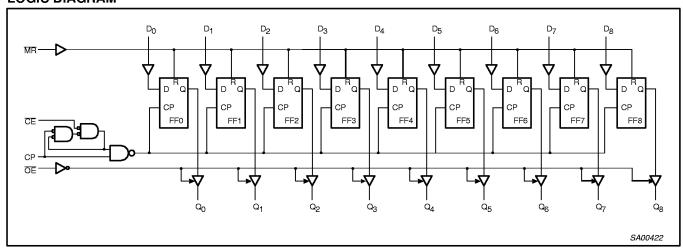


FUNCTIONAL DIAGRAM



SA00421

LOGIC DIAGRAM



9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIM	IITS	UNIT
STIVIBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V	DC supply voltage (for max. speed performance)		2.7	3.6	v
V _{CC}	DC supply voltage (for low-voltage applications)		1.2	3.6	V
VI	DC Input voltage range		0	5.5	V
Vo	DC output voltage range; output HIGH or LOW state		0	V _{CC}	v
	DC output voltage range; output 3-State		0	5.5	
T _{amb}	Operating ambient temperature range in free-air		-40	+85	°C
t _r , t _f	Input rise and fall times	$V_{CC} = 1.2 \text{ to } 2.7V$ $V_{CC} = 2.7 \text{ to } 3.6V$	0 0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS¹

In accordance with the Absolute Maximum Rating System (IEC 134) Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V _{CC}	DC supply voltage		-0.5 to +6.5	٧
I _{IK}	DC input diode current	V _I <0	- 50	mA
VI	DC input voltage	Note 2	-0.5 to +6.5	٧
lok	DC output diode current	$V_{\rm O} > V_{\rm CC}$ or $V_{\rm O} < 0$	± 50	mA
\ <u>'</u>	DC output voltage; output HIGH or LOW state	Note 2	-0.5 to V _{CC} +0.5	V
Vo	DC output voltage; output 3-State	Note 2	-0.5 to 6.5	v
lo	DC output source or sink current	$V_{\rm O}$ = 0 to $V_{\rm CC}$	±50	mA
I _{GND} , I _{CC}	DC V _{CC} or GND current		±100	mA
T _{stg}	Storage temperature range		-65 to +150	°C
P _{TOT}	Power dissipation per package - plastic mini-pack (SO) - plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
 The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions voltages are referenced to GND (ground = 0V)

			ι	IMITS		
SYMBOL	PARAMETER	TEST CONDITIONS	Temp = -	UNIT		
			MIN	TYP ¹	MAX	
V	HIGH level Input voltage	V _{CC} = 1.2V	V _{CC}			_ \
V _{IH}	nian level input voltage	V _{CC} = 2.7 to 3.6V	2.0			\ \ \
V	LOW level Imput voltage	V _{CC} = 1.2V			GND	V
V _{IL}	LOW level Input voltage	V _{CC} = 2.7 to 3.6V			0.8]
		$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -12\text{mA}$	V _{CC} -0.5			
,	LUCI Level autout vella se	$V_{CC} = 3.0V; V_I = V_{IH} \text{ or } V_{IL}; I_O = -100 \mu\text{A}$	V _{CC} -0.2	V _{CC}] ,
V _{OH}	HIGH level output voltage	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -18mA$	V _{CC} -0.6] '
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = -24$ mA	V _{CC} -0.8			
		$V_{CC} = 2.7V; V_I = V_{IH} \text{ or } V_{IL}; I_O = 12\text{mA}$			0.40	
V _{OL}	LOW level output voltage	$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 100\mu A$			0.20	\ \
		$V_{CC} = 3.0V$; $V_I = V_{IH}$ or V_{IL} ; $I_O = 24mA$			0.55	
lı	Input leakage current	V _{CC} = 3.6V; V _I = 5.5V or GND		±0.1	±5	μА
loz	3-State output OFF-state current	$V_{CC} = 3.6V$; $V_I = V_{IH}$ or V_{IL} ; $V_O = 5.5V$ or GND		0.1	±5	μА
I _{off}	Power off leakage supply	$V_{CC} = 0.0V; V_I \text{ or } V_O = 5.5V$		0.1	±10	μА
lcc	Quiescent supply current	$V_{CC} = 3.6V$; $V_I = V_{CC}$ or GND; $I_O = 0$		0.1	10	μА
Δl _{CC}	Additional quiescent supply current per input pin	$V_{CC} = 2.7 \text{V to } 3.6 \text{V}; V_{I} = V_{CC} - 0.6 \text{V}; I_{O} = 0$		5	500	μА

AC CHARACTERISTICS

GND = 0V; t_r = t_f \leq 2.5ns; C_L = 50pF; R_L = 500 Ω ; T_{amb} = -40°C to +85°C.

					L	LIMITS			
SYMBOL	PARAMETER	WAVEFORM	V _{CC}	= 3.3V ±	0.3V	V _{CC} =	= 2.7V	V _{CC} = 1.2V	UNIT
			MIN	TYP ¹	MAX	MIN	MAX	TYP	
t _{PHL} t _{PLH}	Propagation delay CP to Q _n	Figures 1, 4			8.5		9.5		ns
t _{PHL}	Propagation delay MR to Q _n	Figures 1, 4			8.0		8.5		ns
t _{PZH} t _{PZL}	3-State output enable time OE to Q _n	Figures 2, 4			7.0		7.5		ns
t _W	Clock pulse width HIGH or LOW	Figure 1		3.0					ns
t _{SU}	Setup time D _n to CP	Figure 3	1.0	0.3		1.0			ns
t _h	Hold time HIGH or LOW Dn after CP	Figure 3	1.0	-0.2		1.0			ns
f _{max}	Maximum clock pulse frequency	Figure 1	75	150					MHz

NOTE:

All typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.
 The specified overdrive current at the data input forces the data input to the opposite logic input state.

^{1.} Unless otherwise stated, all typical values are at V_{CC} = 3.3V and T_{amb} = 25°C.

9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

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AC WAVEFORMS

 V_M = 1.5V at $V_{CC} \ge 2.7V; \, V_M$ = 0.5 V_{CC} at $V_{CC} < 2.7V.$ V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.

V_X = V_{OL} + 0.3V at V_{CC} \geq 2.7V; V_X = V_{OL} + 0.1 V_{CC} at V_{CC} < 2.7V V_Y = V_{OH} -0.3V at V_{CC} \geq 2.7V; V_Y = V_{OH} - 0.1 V_{CC} at V_{CC} < 2.7V

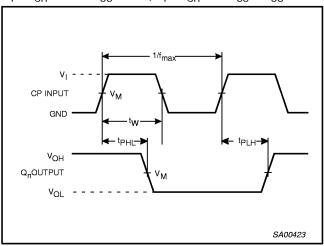


Figure 1. Clock (CP) to output (Q_n) propagation delays, the clock pulse width and the maximum clock pulse frequency.

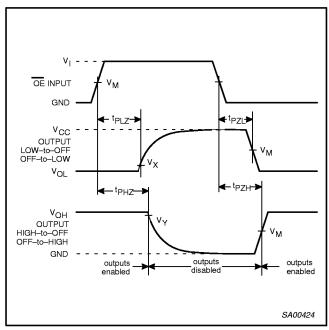


Figure 2. 3-State enable and disable times.

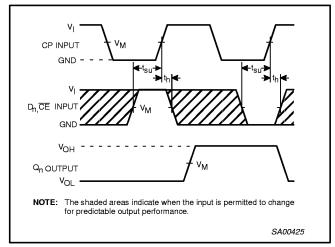


Figure 3. Data setup and hold times for the D_n input and $\overline{\mathsf{CE}}$ input to the CP input.

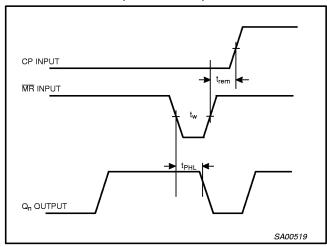


Figure 4. Master reset pulse width, master reset to clock removal time, master reset to output propagation delay.

TEST CIRCUIT

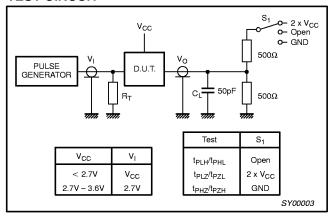


Figure 5. Load circuitry for switching times.

1998 Aug 25 7

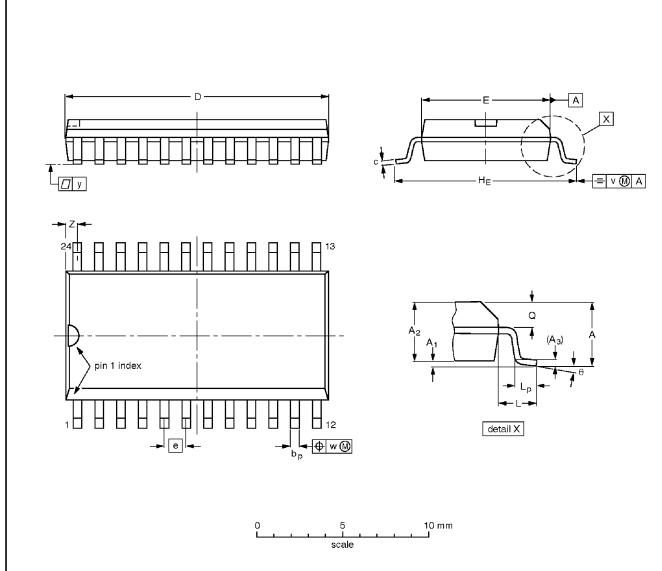
Philips Semiconductors Product specification

9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

SO24: plastic small outline package; 24 leads; body width 7.5 mm

SOT137-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	Α1	A ₂	Аз	Ьp	U	D ⁽¹⁾	E ⁽¹⁾	e	HE	L	Lp	ø	v	w	у	z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	15.6 15.2	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.61 0.60	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	o°

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT137-1	075E05	MS-013AD			-95-01-24 97-05-22

1998 Sep 24 8

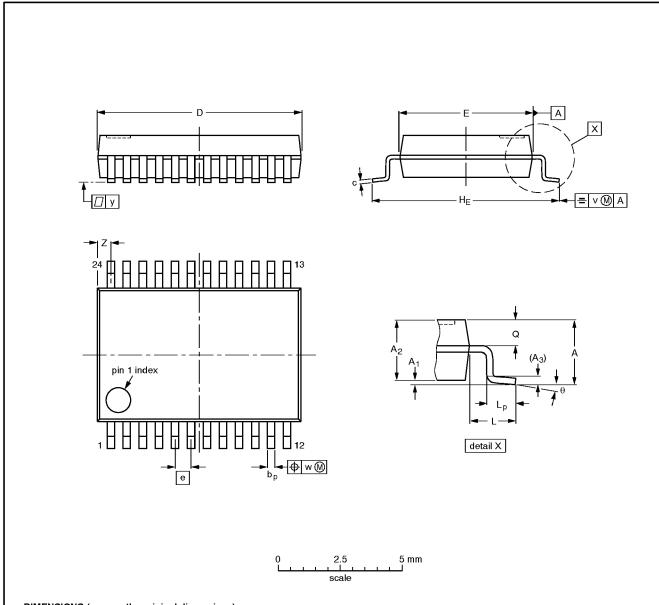
Philips Semiconductors Product specification

9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

plastic shrink small outline package; 24 leads; body width 5.3 mm

SOT340-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	A ₃	рb	c	D ⁽¹⁾	E ⁽¹⁾	е	HE	L	Lp	ø	v	w	у	Z ⁽¹⁾	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	8.4 8.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.8 0.4	8° 0°

Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE		REFER	ENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT340-1		MO-150AG			-93-09-08 95-02-04

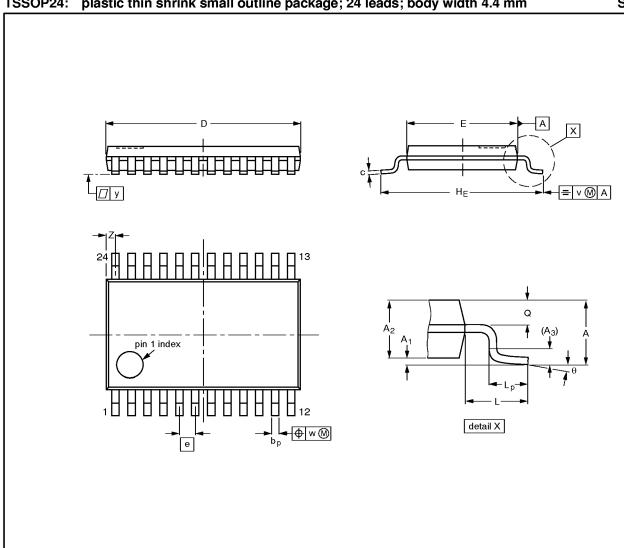
1998 Sep 24 9 Philips Semiconductors Product specification

9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

TSSOP24: plastic thin shrink small outline package; 24 leads; body width 4.4 mm

SOT355-1





DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A ₂	Аз	bр	С	D ⁽¹⁾	E ⁽²⁾	е	HE	L	Lp	œ	v	w	у	Z ⁽¹⁾	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	7.9 7.7	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT355-1		MO-153AD				-93-06-16 95-02-04	

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9-bit D-type flip-flop with 5-volt tolerant inputs/outputs; positive-edge trigger (3-State)

74LVC823A

Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

^[1] Please consult the most recently issued datasheet before initiating or completing a design.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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